	Туре	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	<b>L</b> 1	159	bergman-e\$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/17 08:18	
2	BRS	L2	89346	(clean or cleaning or cleaned or cleaner or cleans or cleansing or cleansed or cleanser) with (semiconductor or wafer or substrate or workpiece)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/17 08:19	
3	BRS	L3	18444 2	(treat or treating or treated or treatment) with (semiconductor or wafer or substrate or workpiece)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/17 08:19	
4	BRS	L4	28734 2	(etch or etching or etched or etchant or strip or stripping stripped or stripper) with (semiconductor or wafer or substrate or workpiece)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/17 08:20	
5	BRS	<b>L</b> 5	35096	(immerse or immersing or immersed or immersion) with (semiconductor or wafer or substrate or workpiece)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/17 08:20	
6	BRS	L6	19165		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/17 08:21	
7	BRS	1./:	31406 5	ultrasonication or ultrasonicate or ultrasonicate or ultrasonicated or sonicating or megasonic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/17 08:23	

	Туре	L #	Hits	Search Text	DBs	Time St	amp	Comments
8	BRS	L8	49569 5	12 or 13 or 14 or 15 or 16	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08 08:23	/17	
9	BRS	L9	23617	18 and 17	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08, 08:23	/17	
10	BRS	L10	90534		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08, 08:25	/17	
11	BRS	L11		or raising or raised or remove or removing or removed) with (wafer or	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/ 08:28	17	
12	BRS	L12	8314	18 same 17	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/ 08:29	17	
13	BRS .	L13	115	l12 same l10		2004/08/ 08:29	17	

	Туре	L#	Hits	Search Text	DBs	Time Stamp	Comments
14	BRS	L15	49507	(134/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/17 08:29	
15	BRS	L16	7	l14 and l1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/17 08:37	
16	BRS	L17	563	semitool\$.asn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/17 08:37	
17	BRS	L18	7	l14 and l17	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/17 08:37	
18	BRS	L14	57	l13 and l11	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/17 09:32	
19	BRS	L19	10724 8	(134/\$ or 34/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/17 09:33	
20	BRS	L20	53	113 and 119	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/17 09:33	
21	BRS	L21	2	6691720.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/17 09:34	-

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	Туре	L #	Hits	Search Text	DBs	Time	Stamp	Comments
22	BRS	L22	3	666844.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/	/08/17 5	
23	BRS	L23	2	6427359.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/	08/17	
24	BRS	L24	7	121 or 122 or 123	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/ 09:44	08/17	
25	BRS	L25	2	6668844.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/ 09:37		
26	BRS	L26	13	l20 and (irradiate or irradiation or irradiation or irradiating or irradiated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/ 09:37	08/17	
27	BRS	L27	14	("20030010352" "20030010 362" "4643774" "4722752"  "4736759" "4977688" "50 90432" "5301701" "556933 0" "5653045" "5950645" " 6299696" "6427359" "6502 591").PN.	USPAT; US-PGPUB	2004/ 09:45	08/17	